

Cover star - avoiding potting voids article

The latest issue of *Global SMT & Packaging* features our White Paper on the cover. **Potting and encapsulating – avoiding voids** was written by Paul Whitehead, our Strategic Accounts Manager. It discusses potting voids – what are they, why they are bad, and how to prevent them happening.



[Click through to read this issue](#), with this and all its other great content.

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